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United States Patent [19]
Hibino

[11] **Patent Number: Des. 435,256**

[45] **Date of Patent: ** Dec. 19, 2000**

[54] **CASE FOR SEMICONDUCTOR ELEMENT**

D. 410,913 6/1999 Saito et al. D14/117

[75] Inventor: **Takuro Hibino**, Tokyo, Japan

OTHER PUBLICATIONS

[73] Assignee: **Sony Corporation**, Japan

Catolog "PICONA," NEC, (Mar. 1997).
Catolog "PowerShot 350, Digital Camera" Canon, (May 1997).
Catolog, "FLASH CARD", Hitachi, (Jul. 1997).
Catolog, "DR-350" Kyocera, (Sep. 1997).

[**] Term: **14 Years**

[21] Appl. No.: **29/090,569**

[22] Filed: **Jul. 10, 1998**

Primary Examiner—M. H. Tung
Attorney, Agent, or Firm—Rader, Fishman & Grauer

[51] **LOC (7) Cl.** **14-02**

[52] **U.S. Cl.** **D14/435**

[58] **Field of Search** D14/114, 117;
D19/9-10; 40/124.01; 283/75-77, 48.1,
83, 107, 901; 235/382.5, 375, 487-94,
441-3; 361/736-7, 752; D13/182; 174/52.1

[57] **CLAIM**

The ornamental design for a case for semiconductor element, as shown and described.

[56] **References Cited**

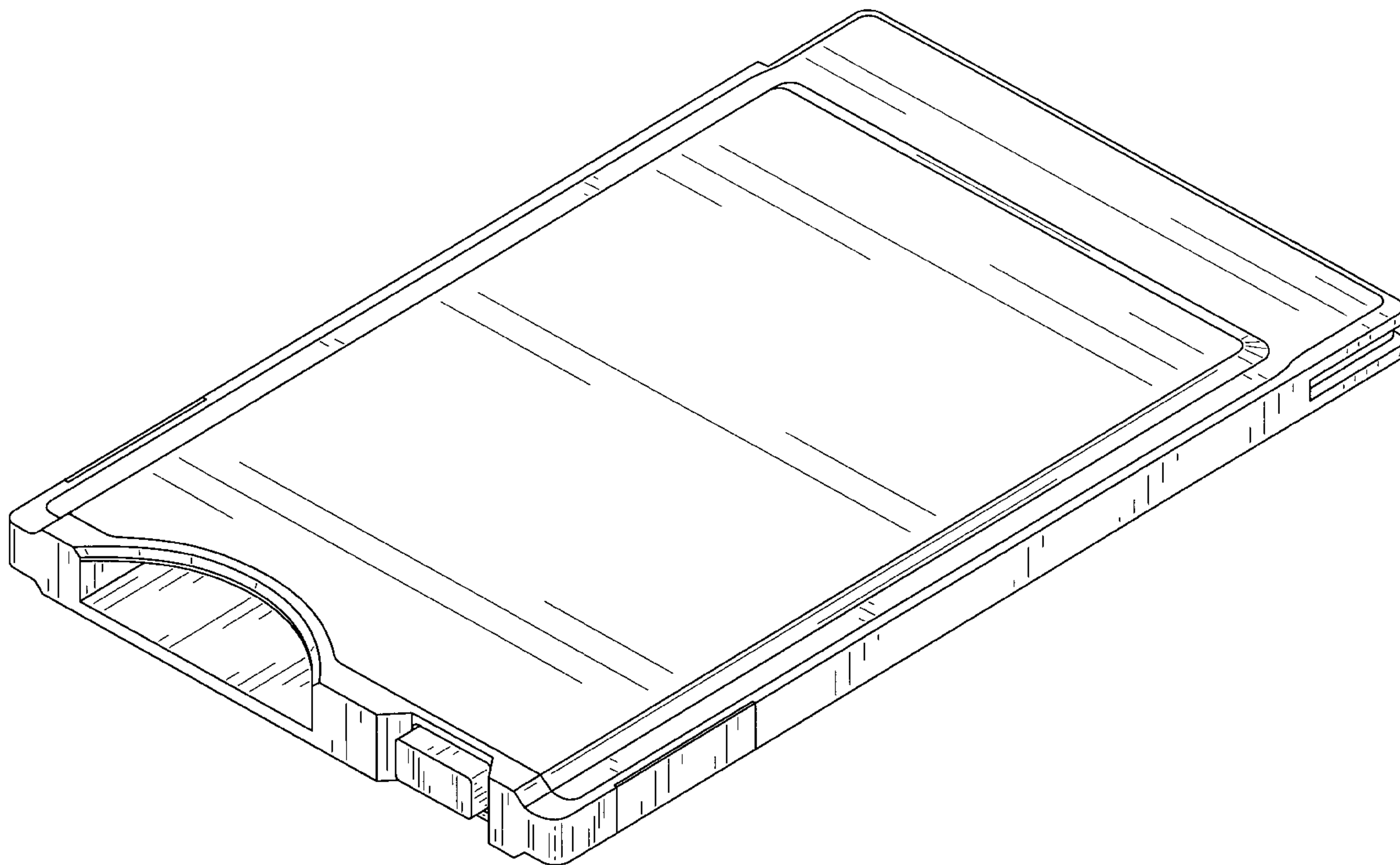
DESCRIPTION

U.S. PATENT DOCUMENTS

- D. 298,326 11/1988 Kimura D14/114
- D. 304,448 11/1989 De La Cruz et al. D14/114
- D. 320,225 9/1991 Ido et al. D14/114 X
- D. 330,022 10/1992 Chen D14/117
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FIG. 1 is a perspective view of a case for semiconductor element showing my new design on an enlarged scale; FIG. 2 is a top plan view thereof; FIG. 3 is a left side elevational view thereof; FIG. 4 is a front elevational view thereof; FIG. 5 is a bottom plan view thereof; FIG. 6 is a right side elevational view thereof; and, FIG. 7 is a rear elevational view thereof.

1 Claim, 5 Drawing Sheets



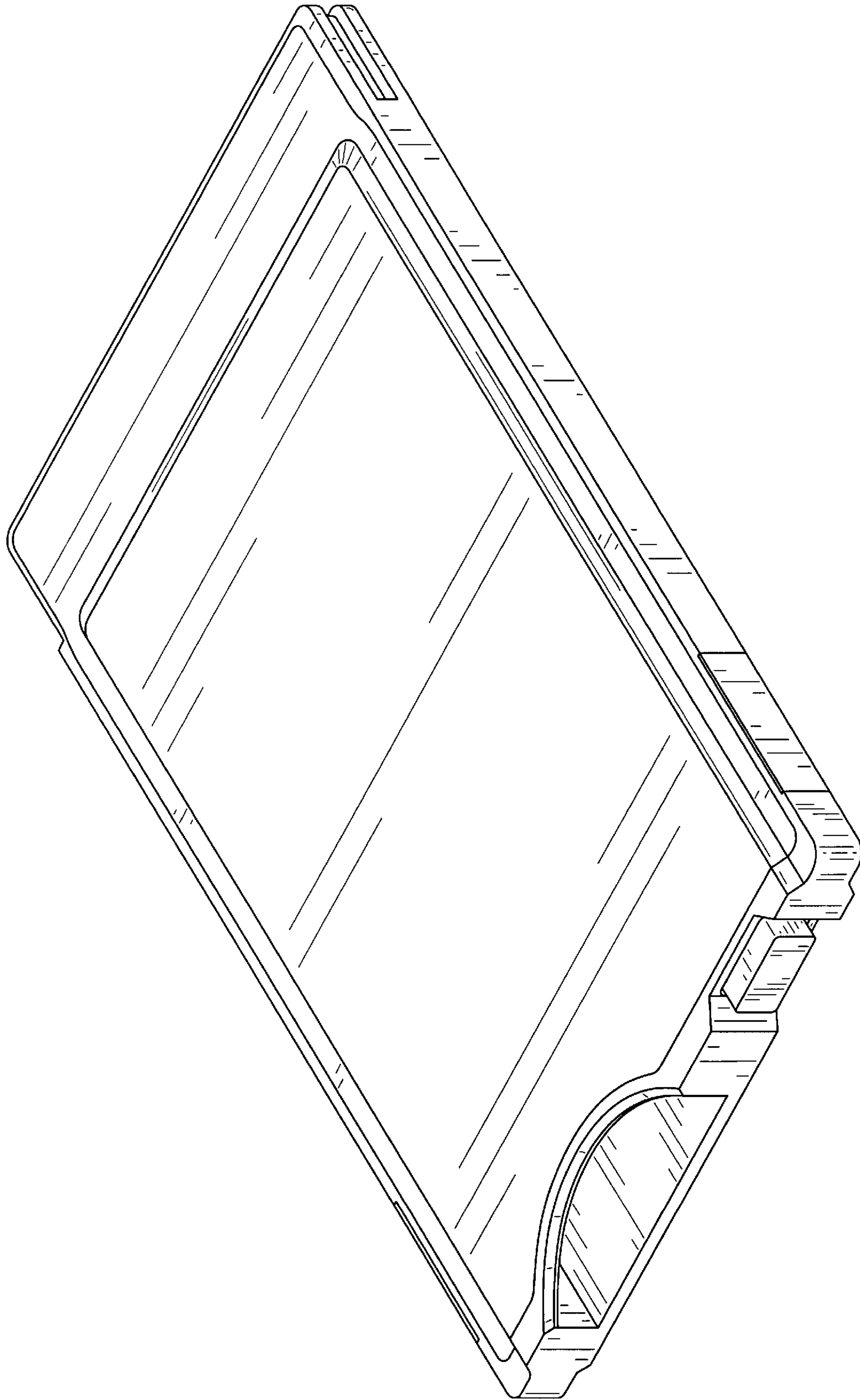


FIG. 1



FIG. 2



FIG. 3

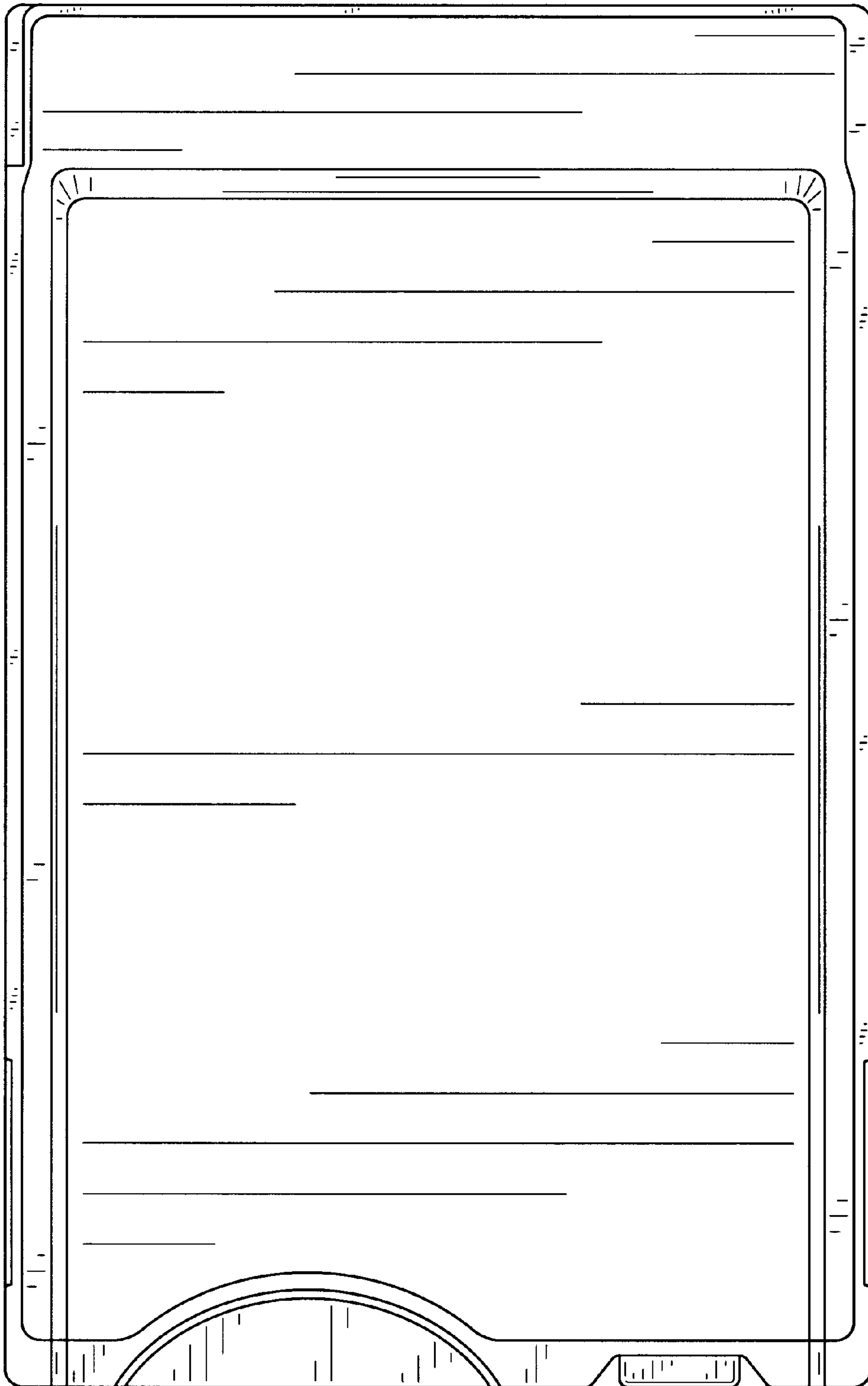


FIG. 4

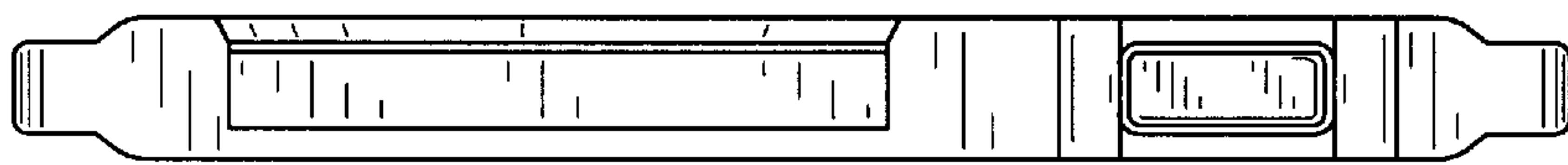


FIG. 5

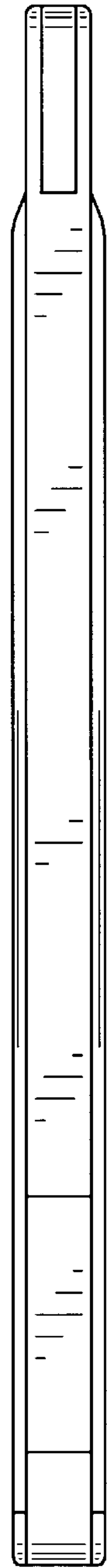


FIG. 6

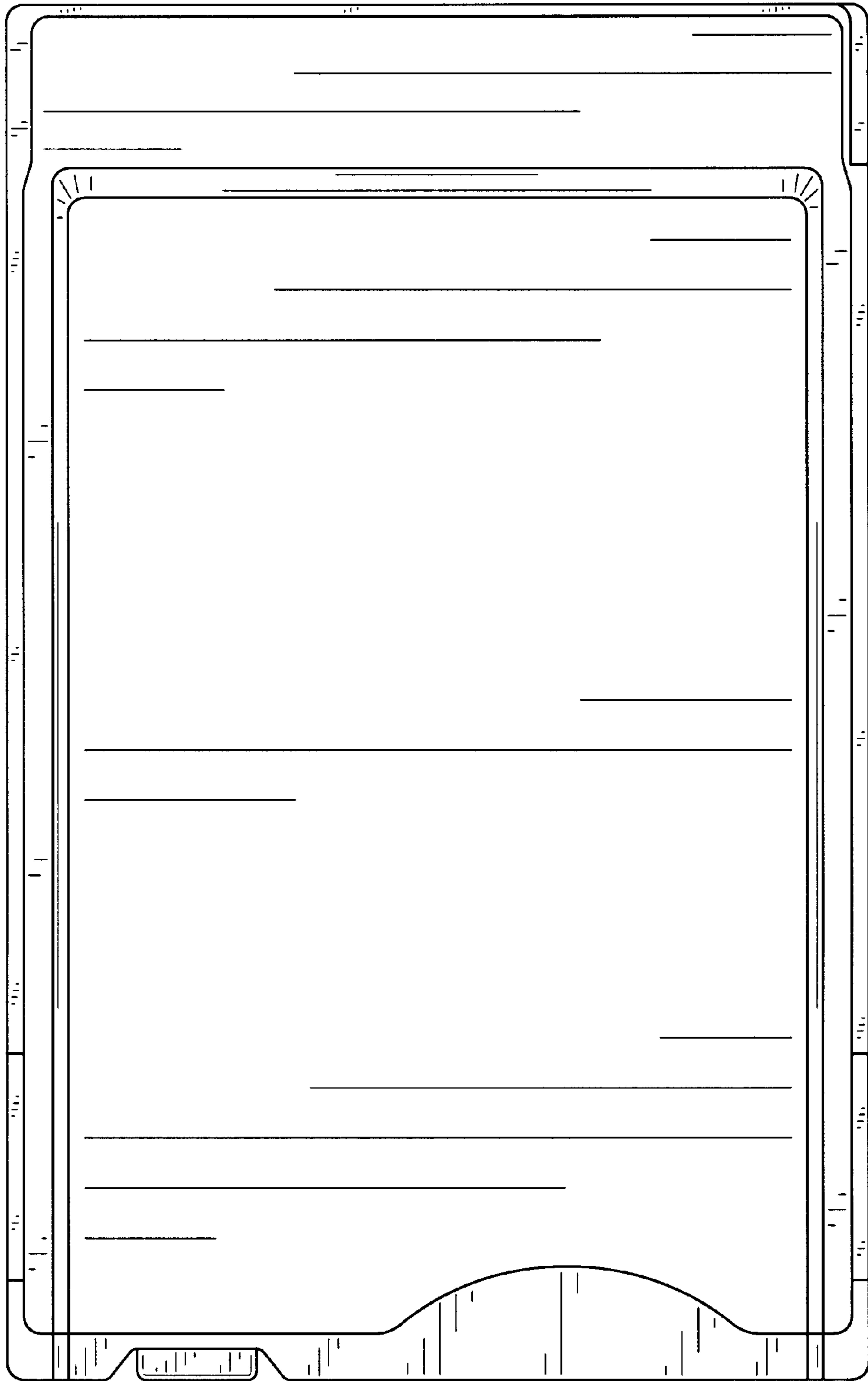


FIG. 7